

RX140 Group

RX140 Flat panel HMI PoC with touch keys and LCD

Introduction

This application note introduces an HMI solution using the RX140 flat panel HMI PoC with touch keys and LCD (hereinafter referred to as "RX140 PoC") to realize touch functionality and serial LCD display.

The sample program described in this application note is configured using the following libraries.

LCD Display : Embedded GUI software emWin (hereinafter referred to as "emWin")

Target Device

RX140 Group

When using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate MCU.

Target Tool

RX140 PoC

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1. Outline

This application note describes the operation and structure of the RX140 PoC. RX140 PoC is equipped with touch buttons, touch slider and LCD (240×320) and can be used as a demonstration to control the display and settings by imagining a microwave oven.

The overall RX140 PoC image is shown below.

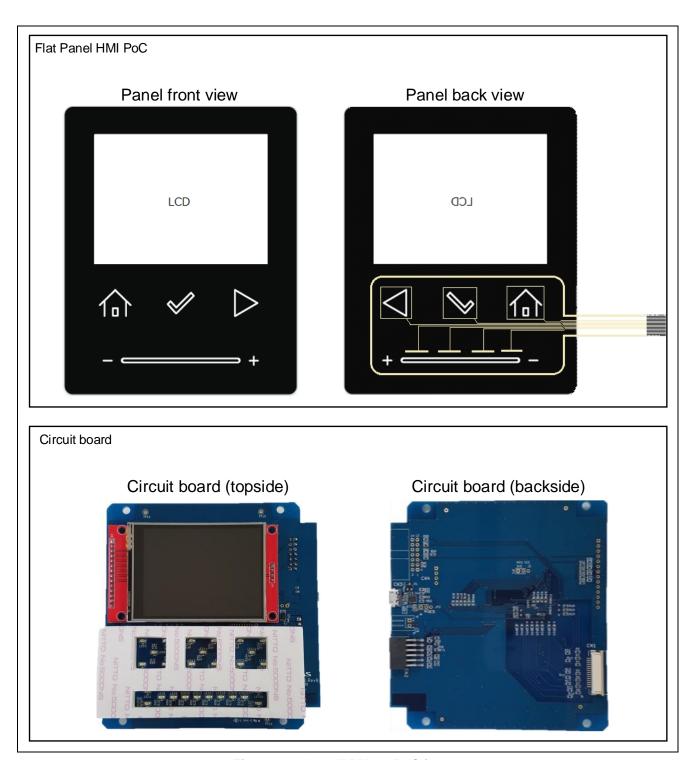


Figure 1-1 Overall RX140 PoC image

The system configuration is shown below.

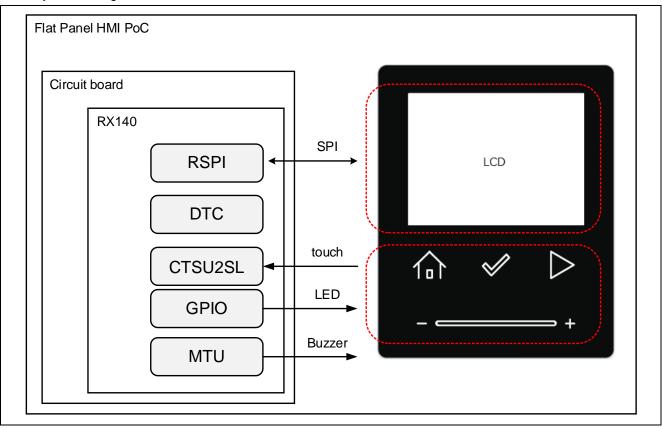


Figure 1-2 System configuration

The software configuration is shown below.

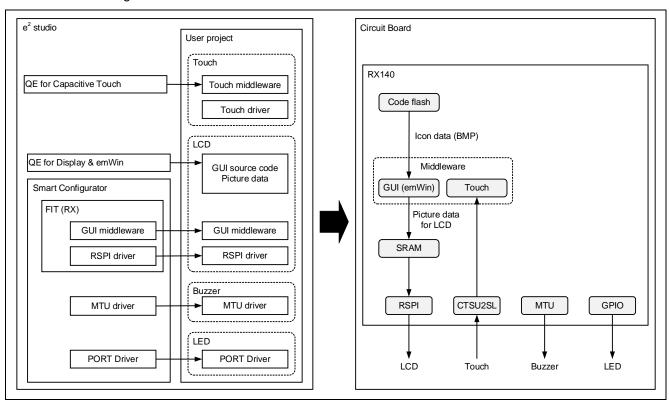


Figure 1-3 Software configuration

2. Operation Confirmation Conditions

The operation of the sample program has been confirmed under the following conditions.

Table 2-1 Operation Confirmation Conditions

Item	Contents	
MCU used	R5F51406ADFM(RX140 Group)	
Operating frequency	Operating frequency (ICLK): 48MHz	
	Peripheral operating frequency (PCLKB) : 24MHz	
Operating voltage	3.3V	
Integrated development	Renesas Electronics	
	e ² studio 2023-01 (23.1.0)	
C compiler	Renesas Electronics	
	C/C++ Compiler Package for RX Family V3.05.00	
	Compiler option	
	— optimize=max	
	— speed	
	— inline=800	
Smart Configurator	RX 2.16.0	
Board support package (r_bsp)	V7.21	
Endian order	Little Endian	
Operating mode	Single chip mode	
Processor mode	Super visor mode	
Sample code version	V1.00	
Emulator	E2 Emulator Lite	

Table 2-2 Operation Confirmation Conditions (LCD)

Item	Contents	
LCD module	2.8 TFT SPI 240 x 320 serial port module	

3. Sample Programs

3.1 Demonstration Screen Flowchart

The demonstration screen flowchart of this sample program is shown below. For detail on each screen, refer to chapter 5.

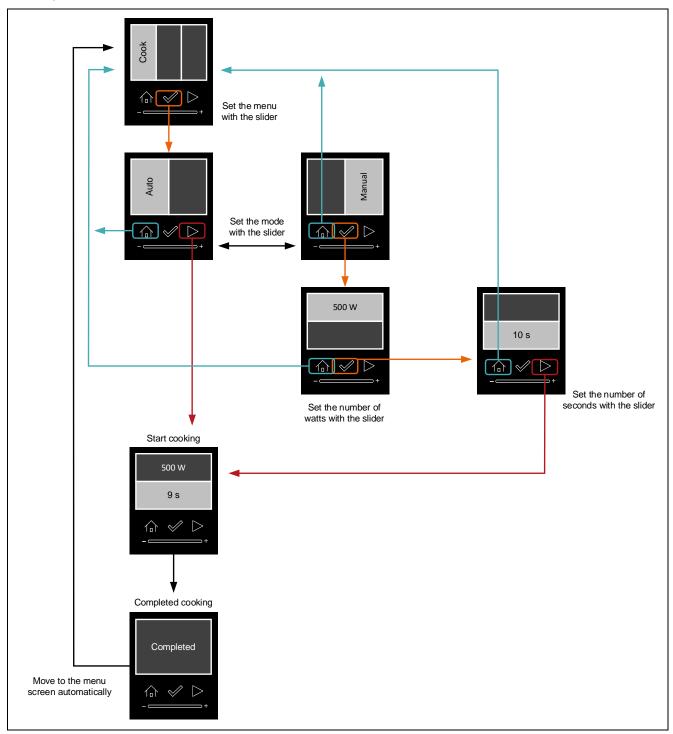


Figure 3-1 Flowchart of demonstration screen (Cook)

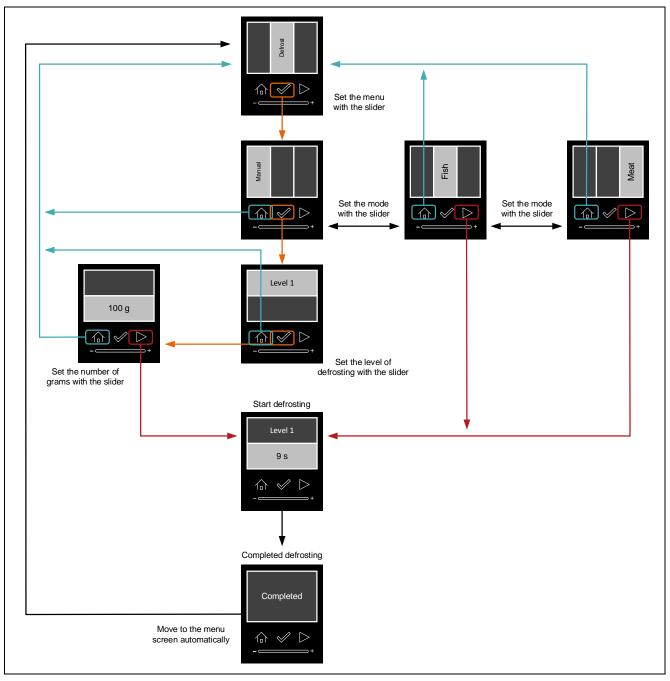


Figure 3-2 Flowchart of demonstration screen (Defrost)

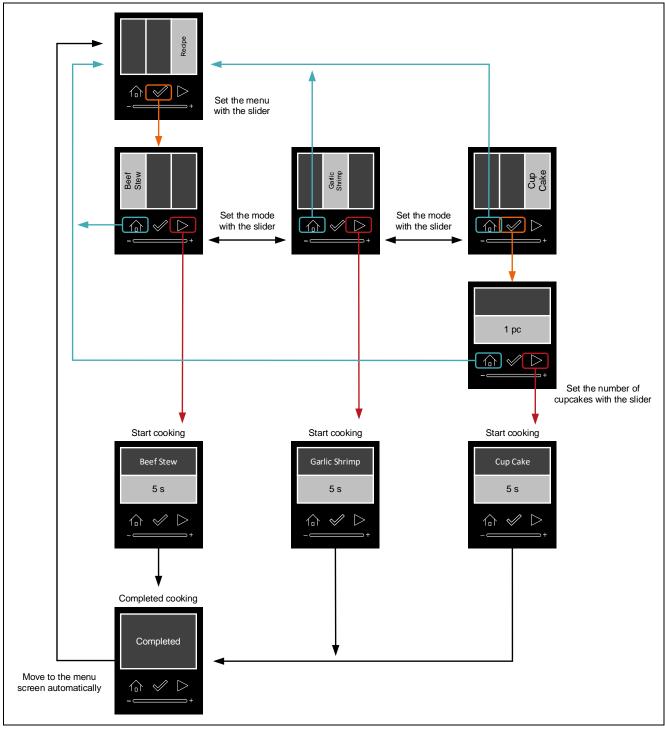


Figure 3-3 Flowchart of demonstration screen (Recipe)

3.2 Flowchart

3.2.1 Overall Flowchart

The overall flowchart is shown below.

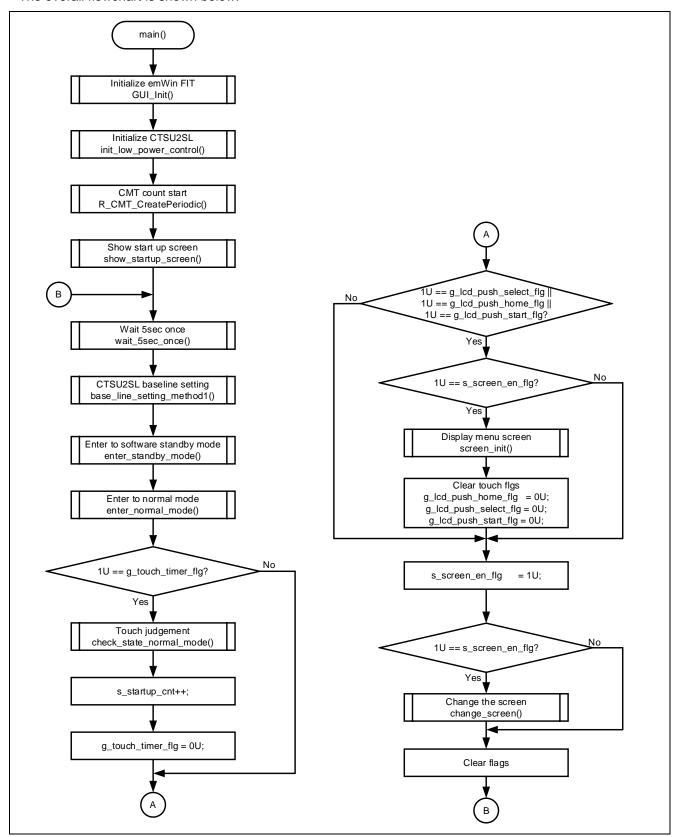


Figure 3-4 Overall flowchart

3.2.2 Processing at touch keys operation

The flowchart for touch keys operation is shown below.

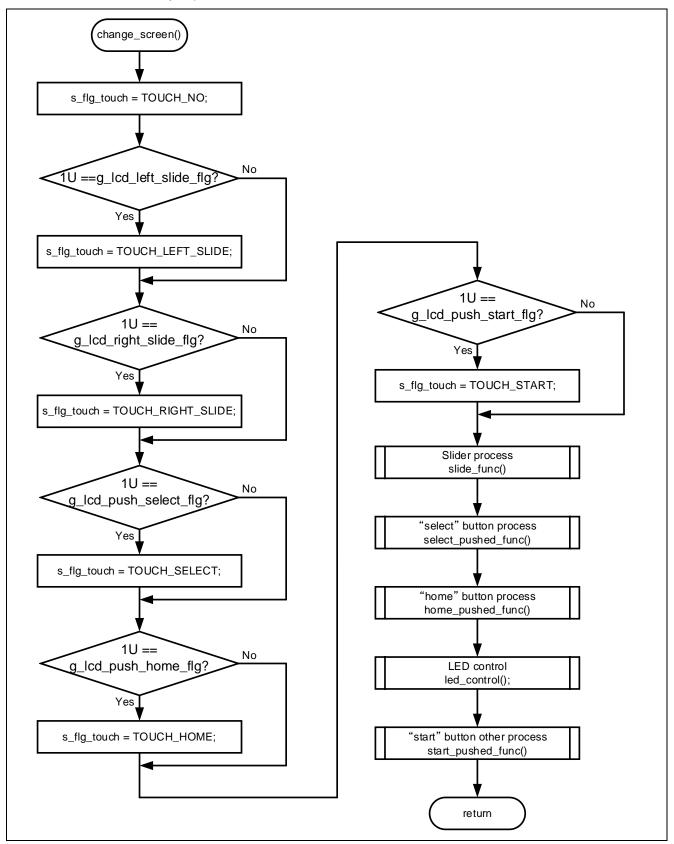


Figure 3-5 Flowchart for touch keys operation

3.2.3 Processing at touch slider operation

The flowchart for touch slider operation is shown below.

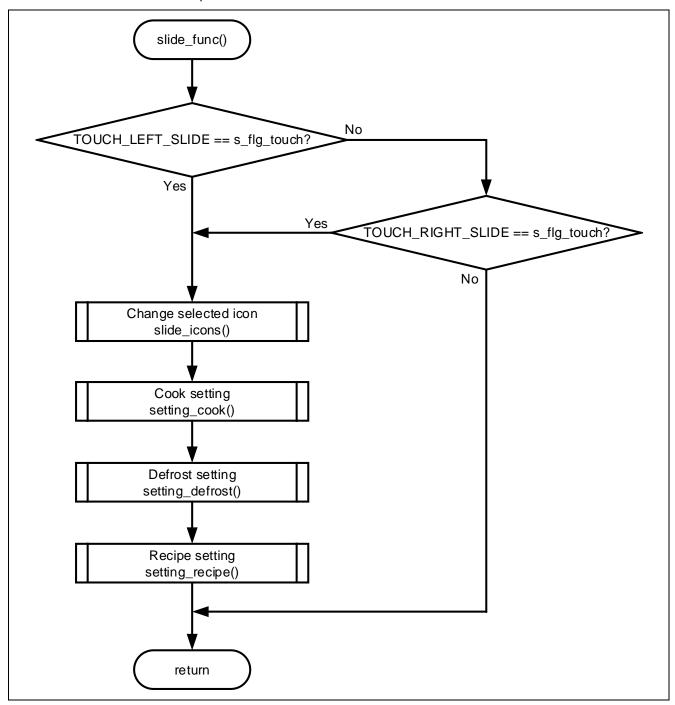


Figure 3-6 Flowchart for touch slider operation

3.2.4 Processing when the "home" button is touched

The flowchart when the "home" button is touched is shown below.

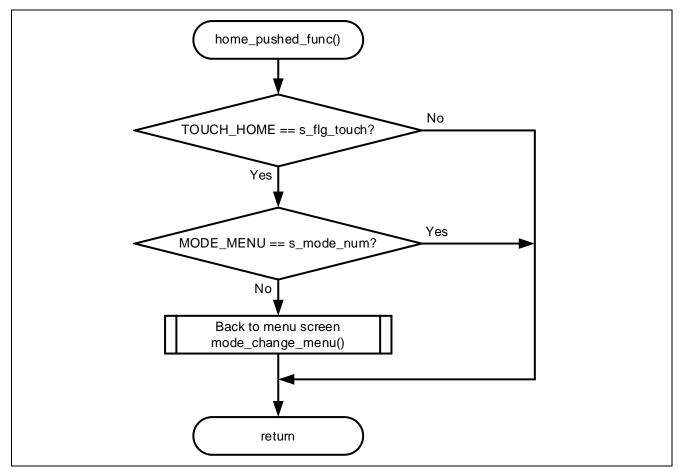


Figure 3-7 Flowchart when the "home" button is touched

3.2.5 Processing when the "select" button is touched

The flowchart when the "select" button is touched is shown below.

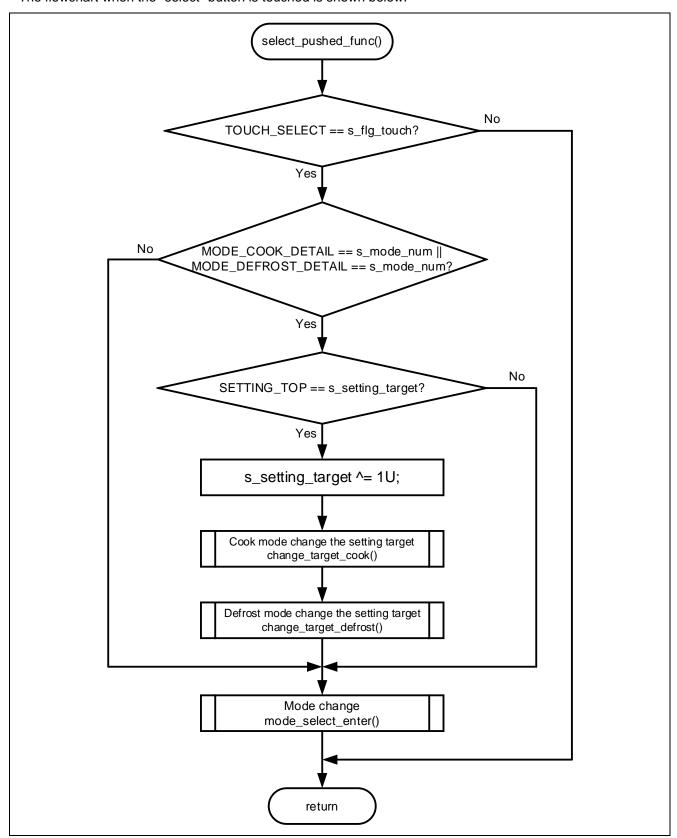


Figure 3-8 Flowchart when the "select" button is touched

3.2.6 Processing when the "start" button is touched

The flowchart when the "start" button is touched is shown below.

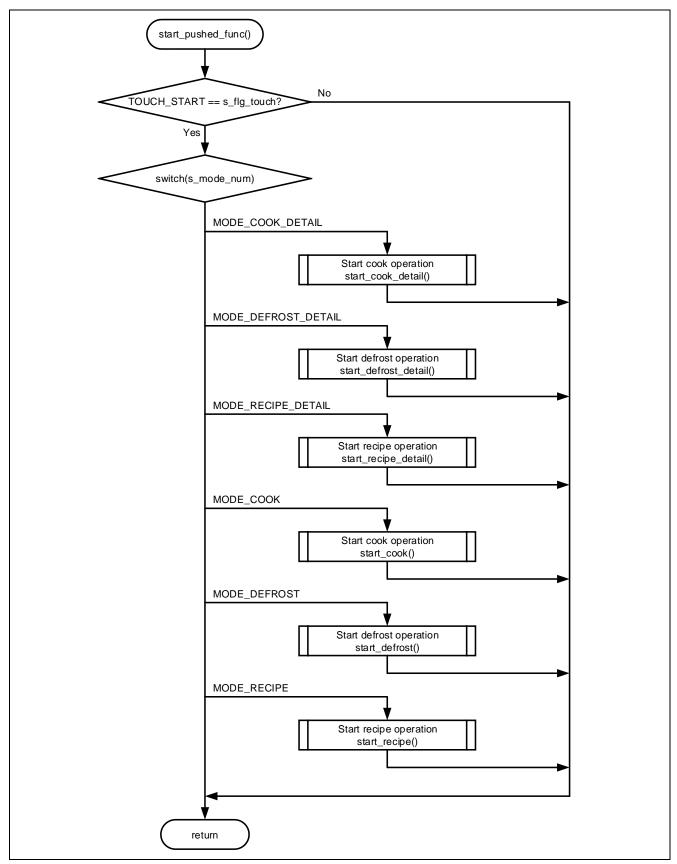


Figure 3-9 Flowchart when the "start" button is touched

3.2.7 Processing of CTSU2SL initialization

The flowchart of CTSU2SL initialization is shown below.

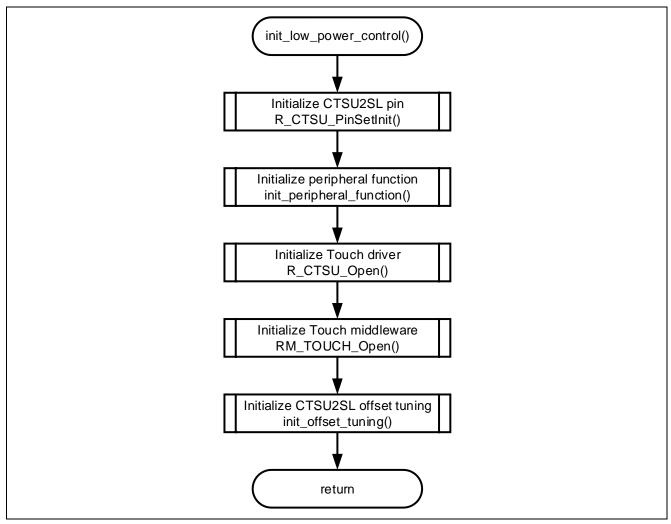


Figure 3-10 Flowchart of CTSU2SL initialization

3.2.8 Processing of CTSU2SL baseline settings

The flowchart of CTSU2SL baseline settings is shown below.

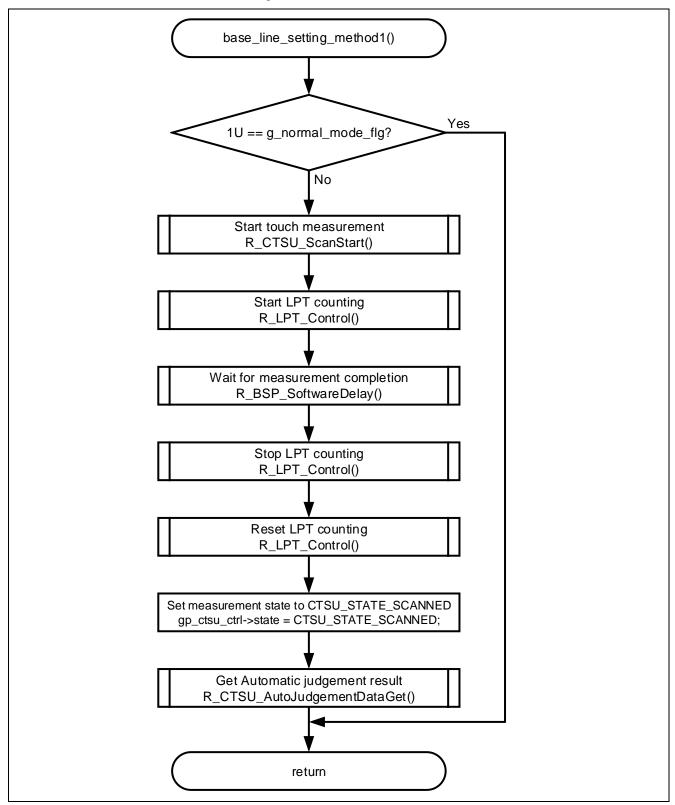


Figure 3-11 Flowchart of CTSU2SL baseline settings

3.2.9 Processing of software standby mode transition and CTSU2SL low power consumption measurement

The flowchart of software standby mode transition and CTSU2SL low power consumption measurement is shown below.

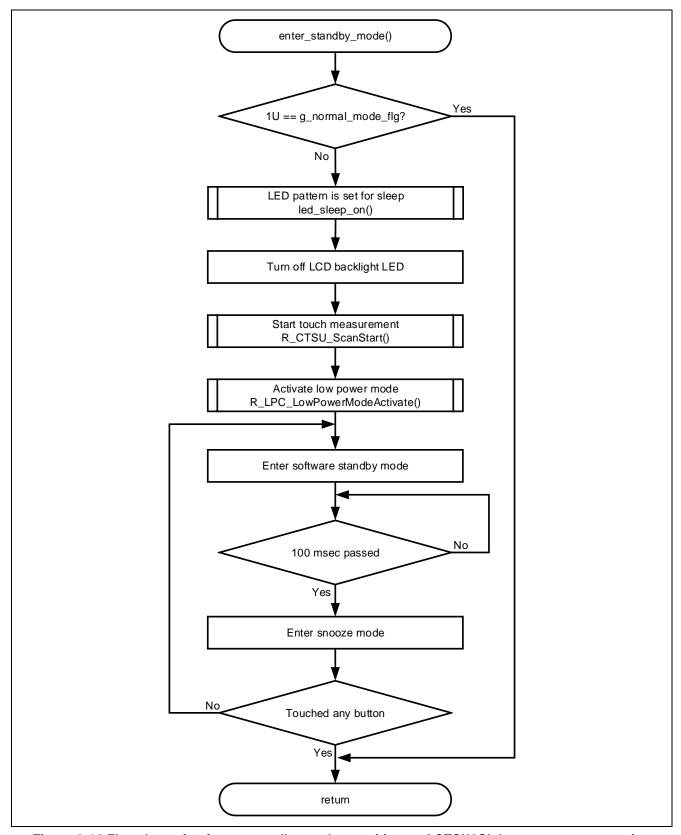


Figure 3-12 Flowchart of software standby mode transition and CTSU2SL low power consumption measurement

3.2.10 Processing of normal operation mode transition

The flowchart of normal operation mode transition is shown below.

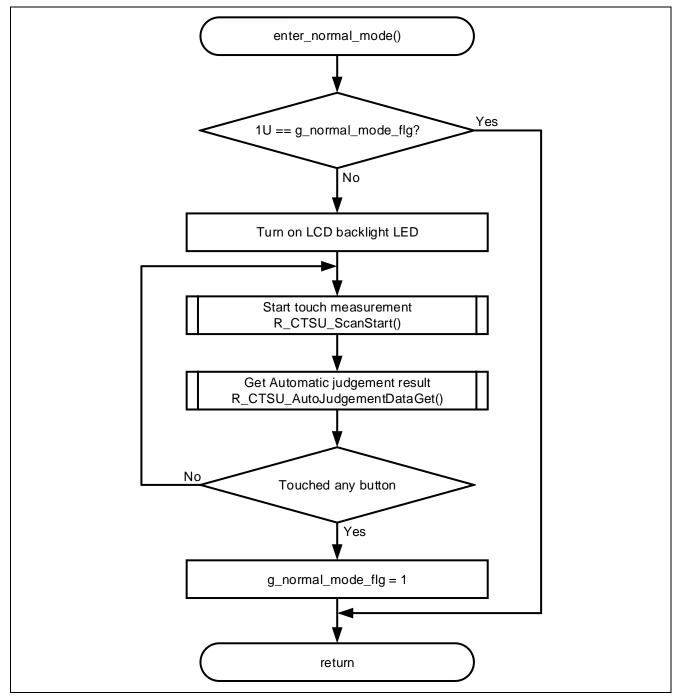


Figure 3-13 Flowchart of normal operation mode transition

3.2.11 Processing of CTSU2SL normal measurement

The flowchart of CTSU2SL normal measurement is shown below.

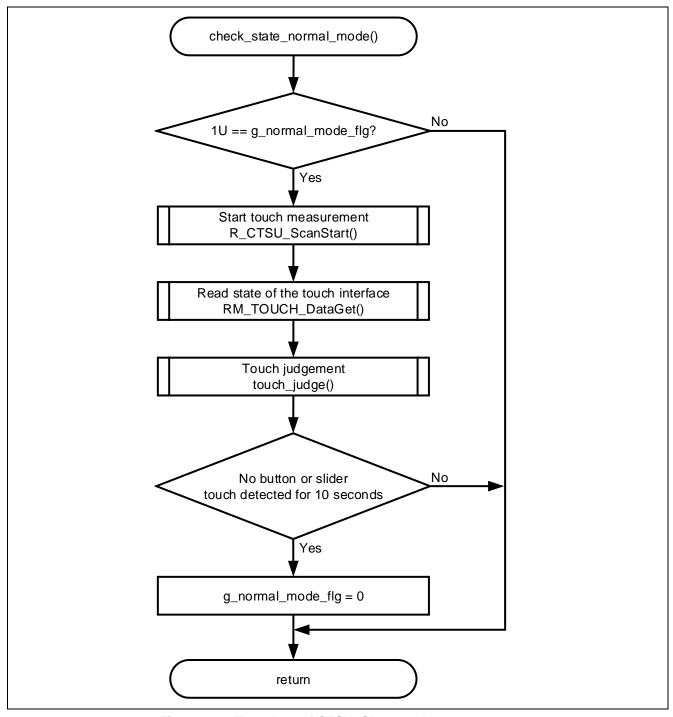


Figure 3-14 Flowchart of CTSU2SL normal measurement

3.2.12 Processing of touch judgement

The flowchart of touch judgement is shown below.

If the left side of the touch slider is touched after touching the right side of the touch slider, the touch slider is judged to have slid to the left. The same is true on the opposite side.

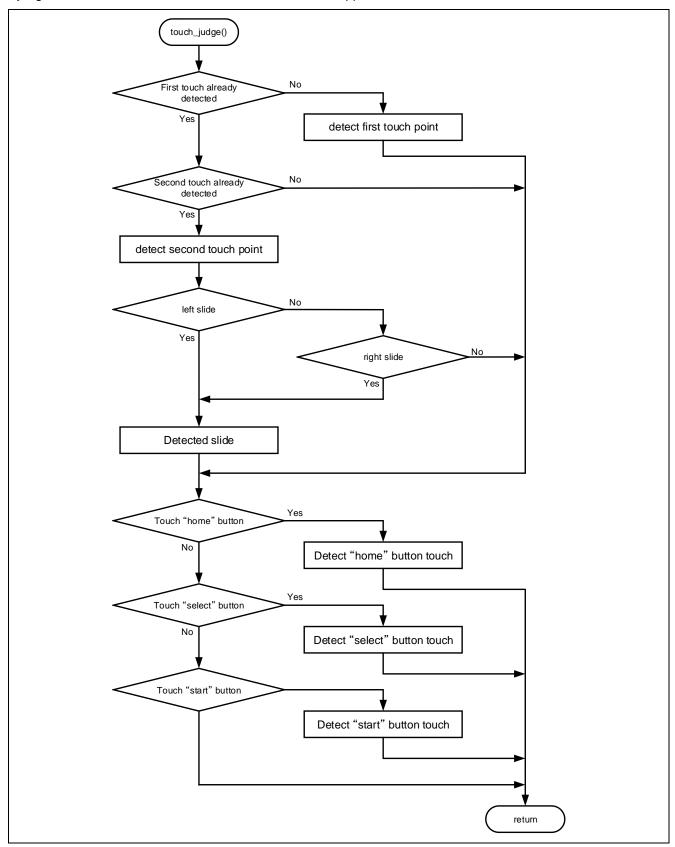


Figure 3-15 Flowchart of touch judgement

3.2.13 Processing of startup screen display

The flowchart of startup screen display is shown below.

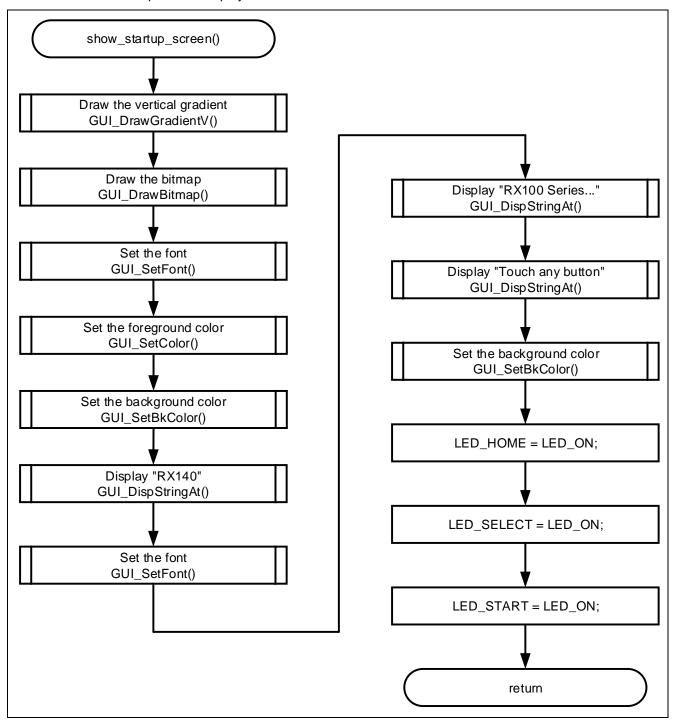


Figure 3-16 Flowchart of startup screen display

3.2.14 Processing of 5 seconds wait

The flowchart of 5 seconds wait is shown below.

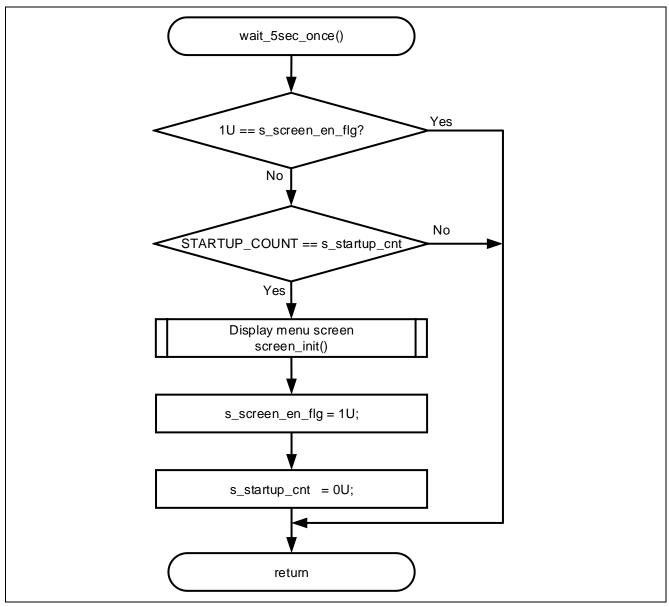


Figure 3-17 Flowchart of 5 seconds wait

3.2.15 Processing of screen initialization

The flowchart of screen initialization is shown below.

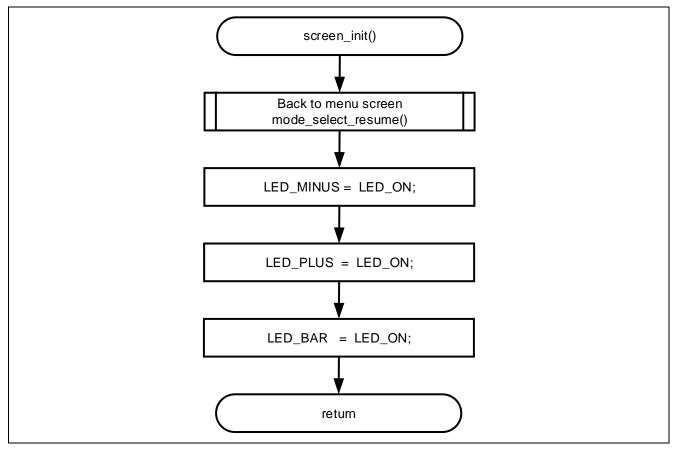


Figure 3-18 Flowchart of screen initialization

3.2.16 Processing of peripheral function initialization

The flowchart of peripheral function initialization is shown below.

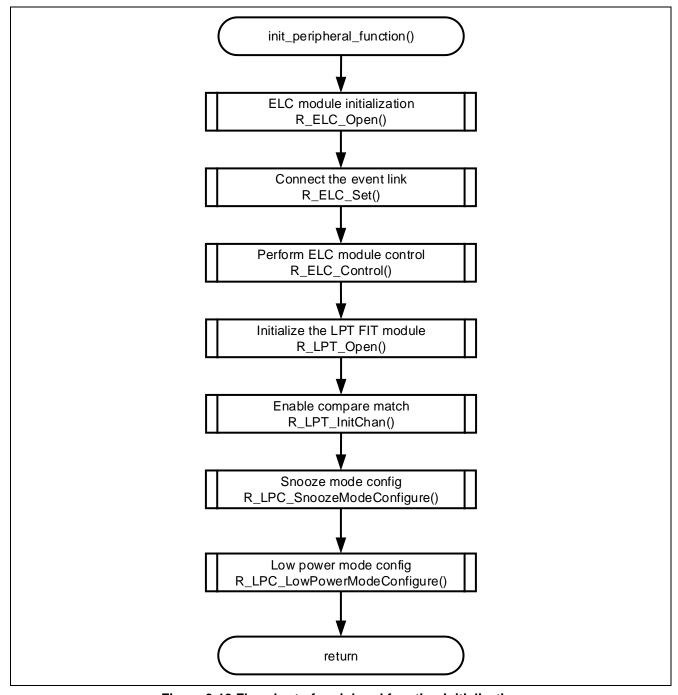


Figure 3-19 Flowchart of peripheral function initialization

3.2.17 Processing of offset initialization for tuning

The flowchart of offset initialization for tuning is shown below.

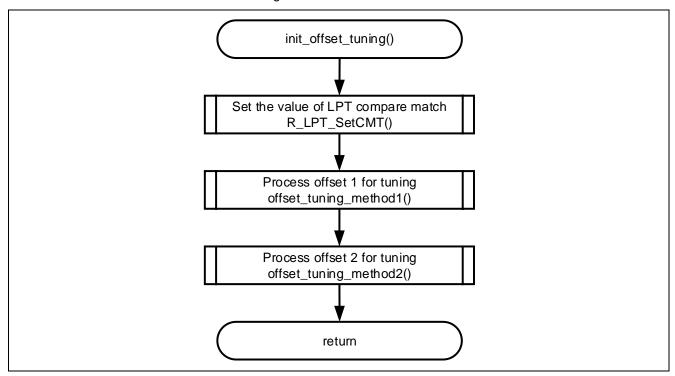


Figure 3-20 Flowchart of offset initialization for tuning

3.2.18 Processing of menu display resumption

The flowchart of menu display resumption is shown below.

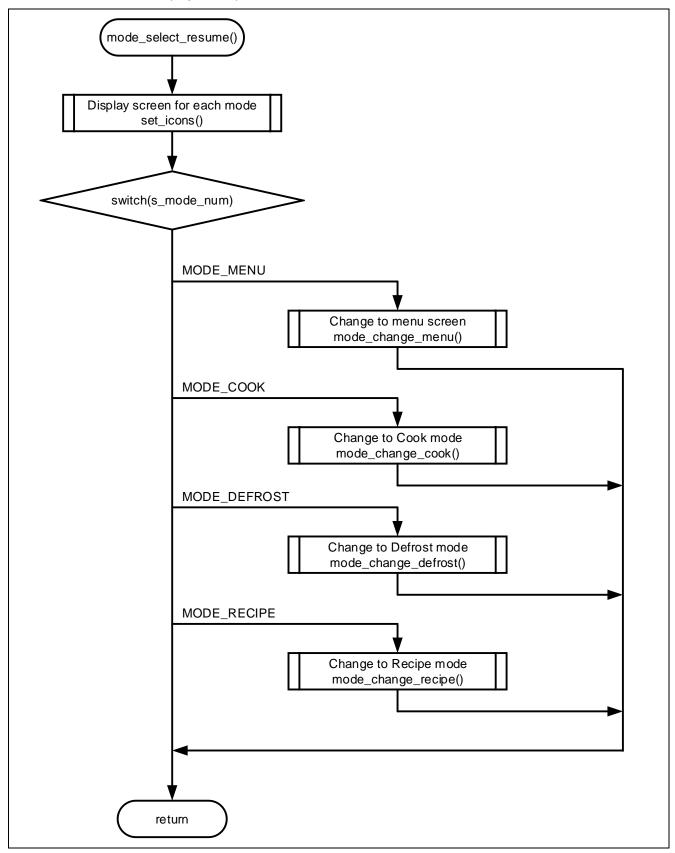


Figure 3-21 Flowchart of menu display resumption

3.2.19 Processing of setting LED pattern to sleep

The flowchart of setting LED pattern to sleep is shown below.

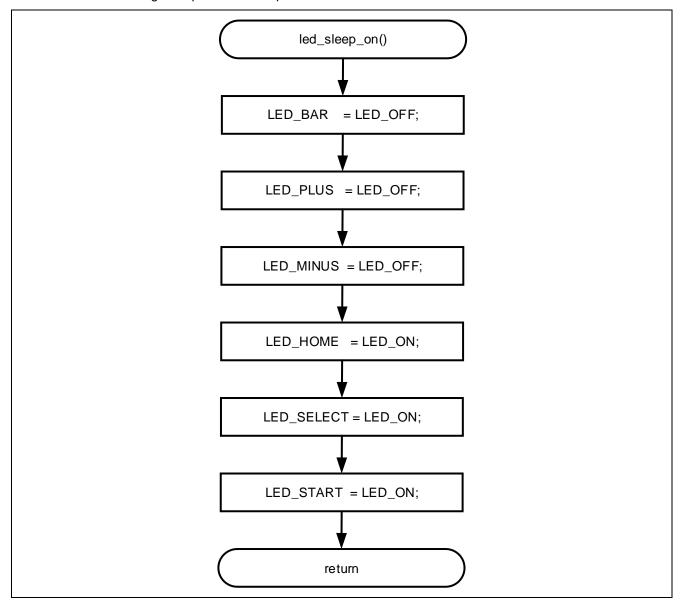


Figure 3-22 Flowchart of setting LED pattern to sleep

3.2.20 Processing of LED control

The flowchart of LED control is shown below.

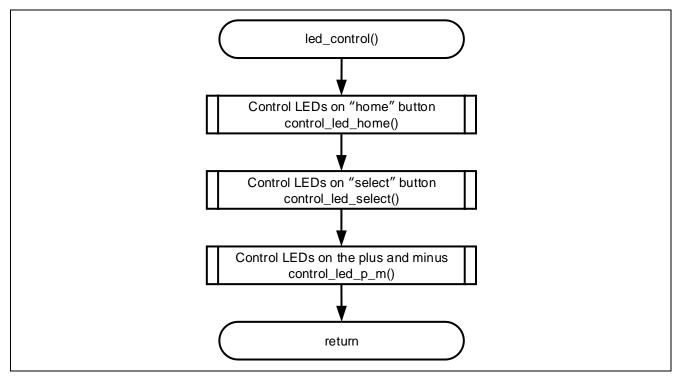


Figure 3-23 Flowchart of LED control

3.3 Pins Used

The following shows lists pins used in this sample program.

Table 3-1 List of Pins and Functions

Pin Name	Input/Output	Function
PB0/RSPCKA	Input/Output	RSPI0 clock pin
PC7/MISOA	Input	RSPI0 MISO pin
PA6/MOSIA	Output	RSPI0 MOSI pin
PC4/TSCAP	-	TSCAP pin
P30/TS2	Input	Electrostatic capacitance measurement pin
P27/TS3	Input	Electrostatic capacitance measurement pin
P26/TS4	Input	Electrostatic capacitance measurement pin
P15/TS5	Input	Electrostatic capacitance measurement pin
PC6/TS14	Input	Electrostatic capacitance measurement pin
PC5/TS15	Input	Electrostatic capacitance measurement pin
PC3/TS16	Input	Electrostatic capacitance measurement pin
PB5/TS20	Input	Electrostatic capacitance measurement pin
P40 ~ P45	Output	LED pin
PB3/MTIO0A	Output	Buzzer pin

3.4 Sample Program Structure

3.4.1 Peripheral Functions Used

The following shows lists peripheral functions used in this sample program.

Table 3-2 List of Peripheral Functions Used and Functions

Peripheral Functions	Function
RSPI0	SPI Communication with LCD
DTC	Used for measure CTSU2SL during snooze mode and RAM to RSPI transfer
ELC	Used for measure CTSU2SL during software standby mode
CTSU2SL	Used for with touch buttons and touch slider
CMT0	Used for inside emWin FIT
CMT2	Used for measure CTSU2SL during normal operation mode
LPT	Used for ELC triggering
PORT	Used for LED
MTU2a	Used for buzzer

3.4.2 Components Used

The following shows lists components used in this sample program.

Table 3-3 List of Components Used

Components	Abbreviation	Version
Board Support Package	r_bsp	7.21
Byte-based circular buffer library	r_byteq	2.10
CMT driver	r_cmt_rx	5.40
Control Low Power States	r_lpc_rx	2.10
CTSU QE API	r_ctsu_qe	2.20
DTC driver	r_dtc_rx	4.21
ELC Driver	r_elc_rx	2.01
GPIO Driver	r_gpio_rx	4.70
Graphic Library with Graphical User Interface	r_emwin_rx	6.32.a.1.00
Low-Power Timer Driver	r_lpt_rx	3.01
PWM Mode Timer	Config_MTU0	1.12.0
RSPI Driver	r_rspi_rx	3.04
Touch QE API	rm_touch_qe	2.20
Port	Config_PORT	2.4.1

3.4.3 Peripheral Function Settings

The Smart Configurator settings used in this sample program are shown below. The items and settings in each table in the Smart Configurator settings are described in the notation on the configuration screen.

Settings not listed are assumed to be default settings.

Table 3-4 Parameters of Smart Configurator (1/3)

Category	Item	Setting/Description	
Smart Configurator >> Clock		The following settings are made on the "Clocks"	
		Tab.	
	VCC	3.3 (V)	
	Main clock	Stopped: Unchecked.	
	HOCO clock	Operation: Checked.	
		HOCO oscillation enabled after reset	
	LOCO clock	Stopped: Unchecked.	
	IWDT dedicated clock	Operation: Checked.	
		Frequency: 15 (kHz)	
	System clock	Clock source: HOCO	
		Flash IF clock (FCLK): 48MHz	
		System clock (ICLK): 48MHz	
		Peripheral module clock (PCLKB): 24MHz	
		Peripheral module clock (PCLKD): 48MHz	
		CLKOUT pin: Unchecked.	
		Low power timer clock (LPTCLK): 15kHz	
Smart Con	figurator >> System	Debugging interfaces setting: FINE	
Smart Con	figurator >> Components >> r_bsp	Other than the changes listed below, default	
		settings are used.	
	Heap size	0x4000	
	Software Interrupt Unit1 (SWINT1)	Used	
	Software Interrupt Task Buffer Number	8	
	Initial value of the software interrupt priority	Priority level 1	
Smart Con	figurator >> Components >> r_dtc_rx	Other than the changes listed below, default settings are used.	
	DMAC FIT check	DMAC FIT modules is not used with DTC FIT module.	
Smart Con	figurator >> Components >> r_elc_rx	Default settings are used.	
	figurator >> Components >> r_ctsu_qe	Other than the changes listed below, default	
	2 2. 1	settings are used.	
	Data transfer of INTCTSUWR and INTCTSURD	DTC	
	Select automatic judgement code	Enable	
	TSCAP pin	Use: Checked.	
	TS2 pin	Use: Checked.	
	TS3 pin	Use: Checked.	
	TS4 pin	Use: Checked.	
	TS5 pin	Use: Checked.	
	TS14 pin	Use: Checked.	
	TS15 pin	Use: Checked.	
	TS16 pin	Use: Checked.	
Smart Configurator >> Components >> r_gpio_rx		Default settings are used.	
Smart Configurator >> Components >> r_lpc_rx		Default settings are used.	

Table 3-5 Parameters of Smart Configurator (2/3)

Category	Item	Setting/Description	
Smart Con	figurator >> Components >> r_rspi_rx	Other than the changes listed below, default settings are used.	
	Dummy data of reception	0x00	
	RSPI channel 0	Used	
	RSPI channel 1	Unused	
	RSPI channel 2	Unused	
	Interrupt priority level of RSPI channel 0	Level 3	
	RSPI0	Checked	
	RSPCKA pin	Use: Checked.	
	MOSIA pin	Use: Checked.	
	MISOA pin	Use: Checked.	
Smart Con	figurator >> Components >> r_cmt_rx	Default settings are used.	
	figurator >> Components >> r_lpt_rx	Other than the changes listed below, default	
Smart Con	ingulator >> Components >> 1_ipt_ix	settings are used.	
	LPT clock source	IWDT-dedicated on-chip oscillator	
Smart Con	figurator >> Components >> rm_touch_qe	Default settings are used.	
Smart Con	figurator >> Components >> r_byteq	Default settings are used.	
Smart Con	figurator >> Components >> r_emwin_rx	Other than the changes listed below, default	
		settings are used.	
	Configurations >> BasicSetting		
	Work area size for GUI	6000	
	Horizontal LCD size	240	
	Vertical LCD size	320	
	Color depth	16 bit per pixel	
	LCD orientation	ORIENTATION_CCW	
	Select DMA transfer modules	DTC	
	Configurations >> Select LCD Interface		
	LCD interface LCD_IF_RSPI		
	Configurations >> Select LCD Interface >> SPI Interface Setting		
	LCD interface channel number	0	
	Select LCD Driver IC	LCD_DRV_IC_ILI9341	
	Communication baud rate of LCD interface	12000000	
	Use or unused display cache	Unuse: Unchecked	
	Configurations >> Select LCD Interface >> LCD Interface Pin Setting		
	Use Display Signal Pin	Use Display Signal Pin	
	Display Signal Pin	GPIO_PORT_A_PIN_1	
	Use Backlight Pin	Use Backlight Pin	
	Backlight Pin	GPIO_PORT_E_PIN_0	
	Use Data/Command Pin	Use Data/Command Pin	
	Data/Command Pin	GPIO_PORT_A_PIN_0	
	Use Chip Select Pin	Use Chip Select Pin	
	Chip Select Pin	GPIO_PORT_4_PIN_7	
	Configurations >> Select Touch Interface		
	Use Touch function	Not use Touch function: Unchecked	

Table 3-6 Parameters of Smart Configurator (3/3)

Category	Item	Setting/Description
Smart Configurator >> Components >> Config_PORT		Other than the changes listed below, default
		settings are used.
	PORT4	Checked.
	P40	Output: Checked
	P41	Output: Checked
	P42	Output: Checked
	P43	Output: Checked
	P44	Output: Checked
	P45	Output: Checked
Smart Con	figurator >> Components >> Config_MTU0	Other than the changes listed below, default
		settings are used.
	Counter clear source	TGRB0 compare match
	MTIOC0A pin	Output initial 0, 1 at compare match
	TGRA initial value	38
	TGRB initial value	188

3.4.4 File Structure

The following shows file structure by sample program.

Table 3-7 File Structure

Folder name, File name	Outline	
Src	Folder for program source	
- main.c	Source file for main processing	
- main.h	Header file for main processing	
- LCD_custom_func.c	Source file for LCD related	
- LCD_custom_func.h	Header file for LCD related	
r_low_power_control.c	Source file for operation mode control related	
r_low_power_control.h	Header file for operation mode control related	
- touch_func.c	Source file for touch related	
- touch_func.h	Header file for touch related	
- Resource	Folder for image and font	
L smc_gen	Smart Configurator generation	
- Config_MTU0		
- Config_PORT		
r_byteq		
- r_cmt_rx		
r_ctsu_qe		
r_dtc_rx		
r_elc_rx		
r_emwin_rx		
r_gpio_rx		
- r_lpc_rx		
r_lpt_rx		
r_rspi_rx		
- rm_touch_qe		
- general		
- r_bsp		
- r_config		
^L r_pincfg		
qe_gen	QE-Touch generation	
QE-Touch		

3.4.5 Variables

The following shows the variables that are used in this sample program.

Table 3-8 List of variables used in the sample code

Variable name	Туре	Contents
g_normal_mode_flg	uint8_t	The Normal operation mode flag
g_touch_timer_flg	uint8_t	The touch judgement start flag in normal operation mode
g_lcd_left_slide_flg	uint8_t	The touch slider slid to the left flag
g_lcd_push_home_flg	uint8_t	Flag indicating that "home" button is touched
g_lcd_push_select_flg	uint8_t	Flag indicating that "select" button is touched
g_lcd_push_start_flg	uint8_t	Flag indicating that "start" button is touched
s_flg_touch	uint8_t	Touch buttons status
s_mode_num	uint8_t	Mode status
s_setting_target	uint8_t	Flags indicating screen status
s_screen_en_flg	uint8_t	Flag indicating initial screen status
s_startup_cnt	uint8_t	Counter for initial screen display time management

3.4.6 Constants

The following shows the constants that are used in this sample program.

Table 3-9 List of constants used in the sample code

Constant Name	Setting Value	Contents	
TOUCH_NO	(0U)	Value at no-operation	
TOUCH_LEFT_SLIDE	(4U)	Value indicating that touch slider is slid to the left	
TOUGH DIGHT CLIDE	(21.1)		
TOUCH_RIGHT_SLIDE	(3U)	Value indicating that touch slider is slid to the right	
TOUCH_SELECT	(1U)	9	
TOOCH_SELECT	(10)	Value indicating that "select" button was touched	
TOUCH_HOME	(2U)	Value at moving to the previous screen	
MODE_MENU	E_MENU (0U) Value of mode not selected		
MODE_RECIPE_DETAIL	(6U)	Value of detail setting in Recipe mode	
MODE_COOK_DETAIL	(3U)	Value of detail setting in Cook mode	
MODE_DEFROST_DETAIL	(4U)	Value of detail setting in Defrost mode	
MODE_COOK	(1U)	Value of start cooking in Cook mode	
MODE_DEFROST	(2U)	Value of start cooking in Defrost mode	
MODE_RECIPE	(5U)	Value of start cooking in Recipe mode	
TOUCH_START	(5U)	Value of execution in each mode	
SETTING_TOP	(0U)	Value of initial screen	
LED_HOME	(PORT4.PODR.BIT.B0)	P40	
LED_SELECT	(PORT4.PODR.BIT.B1)	P41	
LED_START	(PORT4.PODR.BIT.B2)	P42	
LED_MINUS	(PORT4.PODR.BIT.B3)	P43	
LED_BAR	(PORT4.PODR.BIT.B4)	P44	
LED_PLUS	(PORT4.PODR.BIT.B5)	P45	
LED_ON	(1U) Value of LED turning on		
LED_OFF	(0U)	Value of LED turning off	
STARTUP_COUNT	(STARTUP_TIME *	Initial screen display time (Count)	
	CMT_FREQ)		

3.4.7 Functions

The following shows the functions that are used in this sample program.

Table 3-10 List of functions used in the sample code

for low-power measurement initial settings emWin ting start g of startup screen display g of 5 seconds wait baseline settings tandby mode transition eration mode transition gement in normal operation mode	
emWin ing start j of startup screen display j of 5 seconds wait baseline settings tandby mode transition eration mode transition jement in normal operation mode	
ing start of startup screen display of 5 seconds wait baseline settings tandby mode transition eration mode transition gement in normal operation mode	
of startup screen display of 5 seconds wait baseline settings tandby mode transition eration mode transition gement in normal operation mode	
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n update	
of peripheral function initialization	
of offset initialization for tuning	
attern to sleep	
ement	
Processing of menu display resumption	
Processing at touch slider operation	
Processing when "2" button is touched	
Processing when "1" button is touched	
Processing when "2" button is touched	
Processing of LED control	
Processing of offset 1 for tuning	
Processing of offset 2 for tuning	
of screen display for each mode	
e menu screen	
ook mode	
efrost mode	
ecipe mode	
_recipe	
number of watts and seconds in Cook mode	
level of defrosting and the number of grams in Defrost mode	
number of cupcakes in Recipe mode	
pe Setting the number of cupcakes in Recipe mode ct_enter Change the mode and display the LCD screen according to the mode	
Change the setting target of the detail setting screen in Cook mode	
e setting target of the detail setting screen in Defrost mode	
Start cooking in Cook mode	
Start defrosting in Defrost mode	
Start cooking in Recipe mode	
Start of detail setting in Cook mode	
Start of detail setting in Defrost mode	
Start of detail setting in Recipe mode	
Processing LED lighting when "home" button is touched	
Processing LED lighting when "select" button is touched	
htrol_led_select() Processing LED lighting when "select" button is touched htrol_led_p_m() Processing LED lighting when using the touch slider	

3.4.8 Function Specifications

The following shows function specifications that are used in this sample program.

[Function name] main

Outline Main process

Header None

Declaration void main (void)

Description Initializes peripheral functions and controls touch keys and LCD.

Arguments None
Return value None
Remarks None

[Function name] init_low_power_control

Outline CTSU2SL for low-power measurement initial settings

Header r_low_power_control.h

Declaration void init_low_power_control (void)

Description CTSU2SL for low-power measurement initial settings.

Arguments None Return value None Remarks None

[Function name] GUI_Init

Outline Initializing emWin

Header GUI.h

Declaration void GUI_Init (void)

Description Initializes emWin internal data structures and variables.

Arguments None Return value None Remarks None

[Function name] show_startup_screen

Outline Processing of startup screen display

Header R_low_power_control.h

Declaration void show_startup_screen (void) **Description** Performs startup screen display.

Arguments None Return value None Remarks None

[Function name] base_line_setting_method1

Outline CTSU2SL baseline settings
Header r_low_power_control.h

Declaration void base_line_setting_method1 (void)

Description CTSU2SL baseline settings.

ArgumentsNoneReturn valueNoneRemarksNone



[Function name] enter_standby_mode

Outline Software standby mode transition

Header r_low_power_control.h

Declaration void enter_standby_mode (void)

Description Turn off LCD panel backlight and transition to software standby mode.

Arguments None Return value None Remarks None

[Function name] enter_normal_mode

Outline Normal operation mode transition

Header r low power control.h

Declaration void enter_normal_mode (void)

Description Turn on LCD panel backlight and transition to normal operation mode.

Arguments None Return value None Remarks None

[Function name] check_state_normal_mode

Outline Touch judgement in normal operation mode

Header r_low_power_control.h

Declaration void check state normal mode (void)

Description Performs touch judgement in normal operation mode.

Arguments None
Return value None
Remarks None

[Function name] screen_init

Outline Processing of screen initialization

HeaderLCD_custom_func.hDeclarationvoid screen_init (void)DescriptionPerforms screen initialization.

Arguments None Return value None Remarks None

[Function name] change_screen

OutlineLCD screen updateHeaderLCD_custom_func.hDeclarationvoid change_screen (void)

Description Updates the LCD screen by touch operation.

Arguments None Return value None Remarks None



[Function name] led_sleep_on

Outline Set LED pattern to sleep Header LCD_custom_func.h **Declaration** void led_sleep_on (void) **Description** Sets LED pattern to sleep

Arguments None None Return value None **Remarks**

[Function name] touch_judge

Outline Touch judgement Header touch_func.h

Declaration void touch_judge (uint64_t button_status, uint16_t slider_position) **Description** Performs touch judgement and sets the judgement result to a flag.

Arguments button_status, slider_position

Return value None None Remarks

3.4.9 ROM/RAM usage

ROM/RAM usage for this sample program is shown below.

Table 3-11 ROM usage

Size (KByte)	description	
63	LCD Graphic data	
112	emWin, LCD control	
16	Touch (sleep)	
17	demo program	
27	Other	
Total 235Kbyte	MAX 256Kbyte (91.7% Used)	

Table 3-12 RAM usage

Size (KByte)	Description	
25	bitmap work area	
16	heap area	
6	emWin work area	
8	Other	
Total 55KByte	MAX 64KByte (86% Used)	

4. Importing a Project

The sample programs are distributed in e² studio project format. This section shows how to import a project into e² studio or CS+. After importing a project, check the build and debug settings.

4.1 Procedure in e² studio

To use sample programs in e^2 studio, follow the steps below to import them into e^2 studio. In projects managed by e^2 studio, do not use space codes, multibyte characters, and symbols such as "\$", "#", "%" in folder names or paths to them.

(Note that depending on the version of e² studio you are using, the interface may appear somewhat different from the screenshots below.)

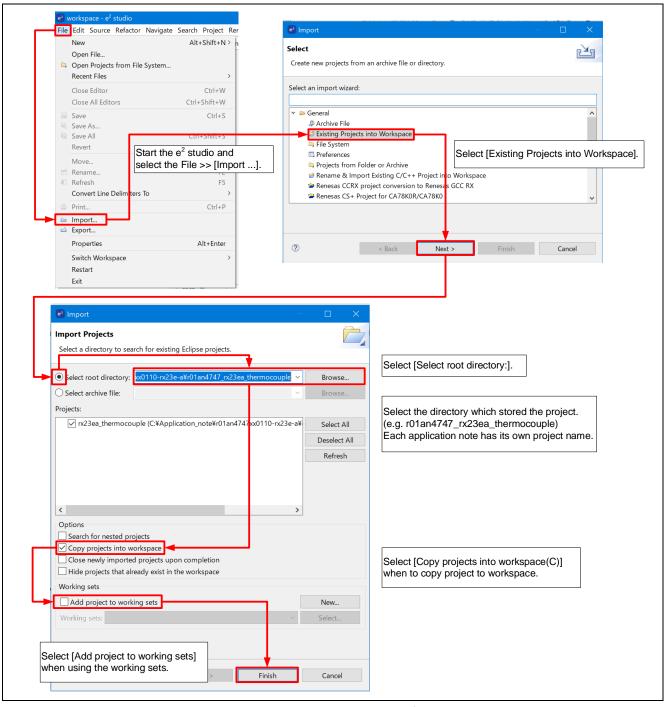


Figure 4-1 Import a Project into e² Studio

4.2 Procedure in CS+

To use sample programs in CS+, follow the steps below to import them into CS+. In projects managed by CS+, do not use space codes, multibyte characters, and symbols such as "\$", "#", "%" in folder names or paths to them.

(Note that depending on the version of CS+ you are using, the interface may appear somewhat different from the screenshots below.)

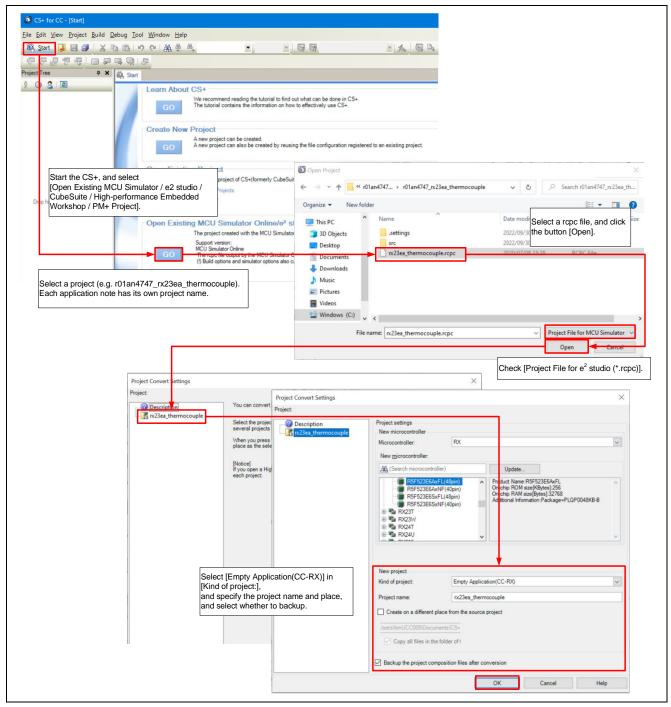


Figure 4-2 Import a Project into CS+

5. Start Demonstration

Disconnect the E2 Emulator Lite and turn on the RX140 PoC to start the demonstration program. This demonstration program assumes control of the display and settings of a microwave oven. Set the cooking conditions and recipe selections using the touch buttons and touch slider while checking the LCD.

Hereinafter, touch buttons are described as buttons and touch slider is described as slider.

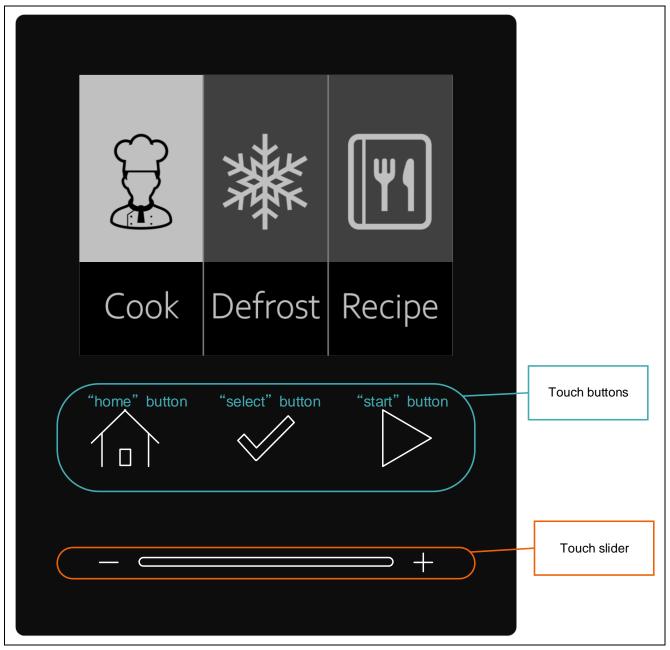


Figure 5-1 Demonstration screen and operation panel

5.1 Powered on RX140 PoC and menu screen

When RX140 PoC is powered on, the LCD panel displays the RX logo and RX140 features (initial screen) for approximately 5 seconds. When the display finishes, the sample program starts and becomes a menu screen.

And while the initial screen is displayed, can immediately move to the menu screen by touching any button.

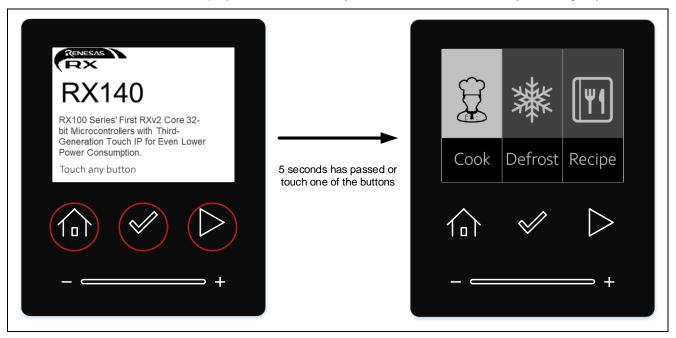


Figure 5-2 Start of the demonstration

5.2 Menu screen

"Cook", "Defrost" or "Recipe" can be selected with the slider operation on the menu screen.

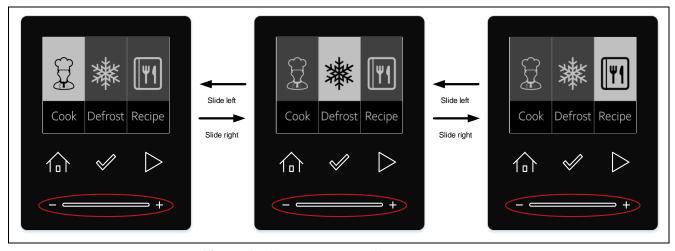


Figure 5-3 How to operate the menu screen

5.3 Cook setting

5.3.1 Move to mode selection screen

While "Cook" is selected on the menu screen, touching the "select" button can move to the Cook mode selection screen.

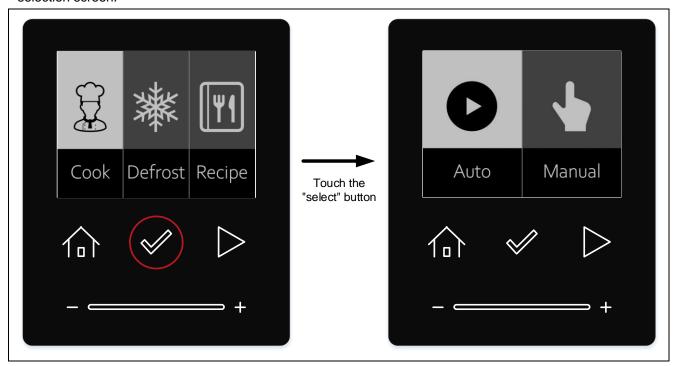


Figure 5-4 Move to the Cook mode selection screen

5.3.2 Select mode

Apr.24.23

While the Cook mode selection screen is displayed, "Auto" or "Manual" can be selected with the slider operation.

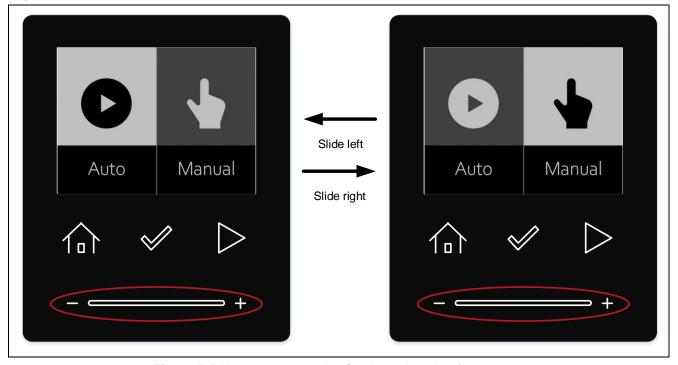


Figure 5-5 How to operate the Cook mode selection screen

5.3.3 Select Auto

While "Auto" is selected on the Cook mode selection screen, touching the "start" button can start cooking.

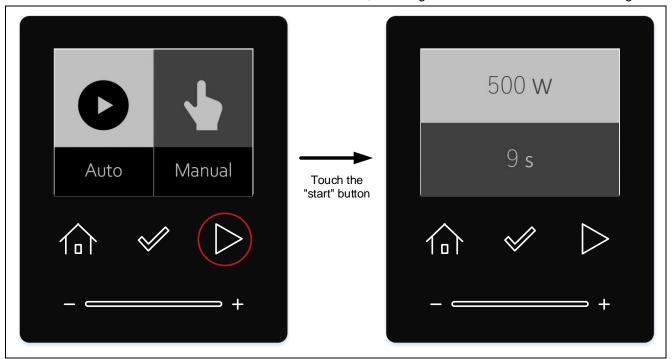


Figure 5-6 Start cooking in Auto mode

5.3.4 Select Manual

While "Manual" is selected on the Cook mode selection screen, touching the "select" button can move to the Cook detail setting screen.

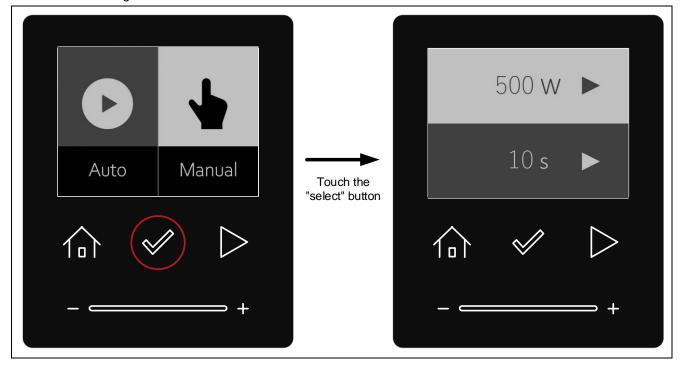


Figure 5-7 Move to the Cook detail setting screen

5.3.4.1 Set the number of watts

While the cursor is on the upper side, the number of watts can be set with the slider. "500W", "600W" and "700W" can be selected as the power level.

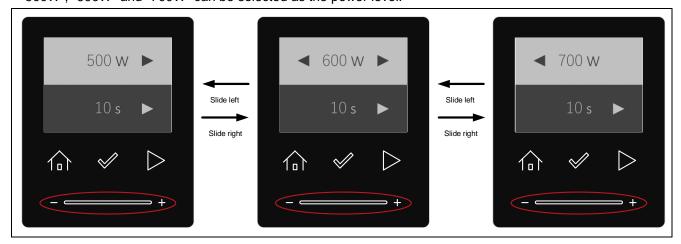


Figure 5-8 Setting the number of watts

5.3.4.2 Move the cursor

While the Cook detail setting screen is displayed, touching the "select" button can move the cursor. The item with a light-colored background is selected.

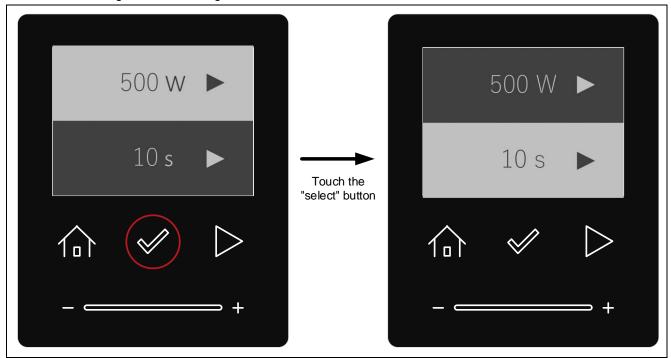


Figure 5-9 How to operate the cursor on the Cook detail setting screen

5.3.4.3 Set the number of seconds

While the cursor is on the lower side, the number of seconds can be set with the slider. "10s", "20s" and "30s", can be selected as the cooking time.

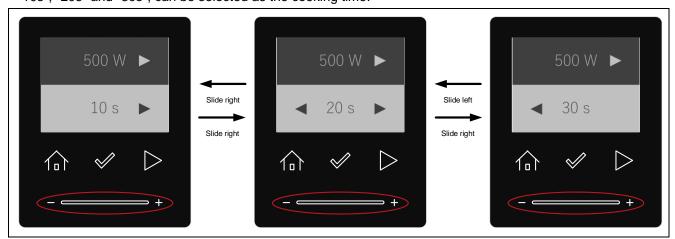


Figure 5-10 Setting the number of seconds

5.3.4.4 Start cooking

While the Cook detail setting screen is displayed and the cursor is on the lower side, touching the "start" button can start cooking.

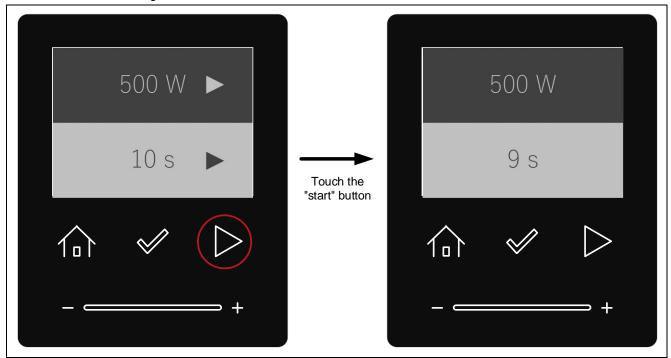


Figure 5-11 Start cooking in Manual mode

5.4 Defrost setting

5.4.1 Move to mode selection screen

While "Defrost" is selected on the menu screen, touching the "select" button can move to the Defrost mode selection screen.

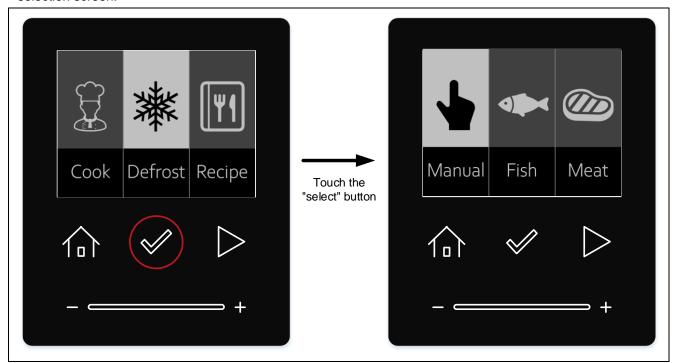


Figure 5-12 Move to the Defrost mode selection screen

5.4.2 Select mode

While the Defrost mode selection screen is displayed, "Manual", "Fish" or "Meat" can be selected with the slider operation.

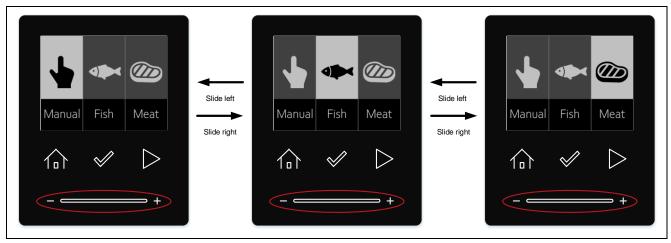


Figure 5-13 How to operate the Defrost mode selection screen

5.4.3 Select Manual

While "Manual" is selected on the Defrost mode selection screen, touching the "select" button can move to the Defrost detail setting screen.

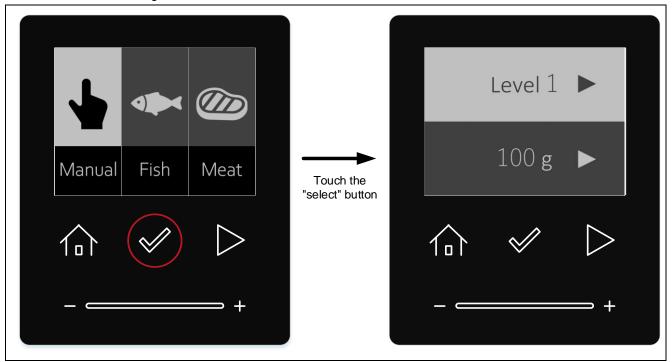


Figure 5-14 Move to the Defrost detail setting screen

5.4.3.1 Set the level of defrosting

While the cursor is on the upper side, the level of defrosting can be set with the slider. "Level1", "Level2" and "Level3" can be selected as the defrosting level.

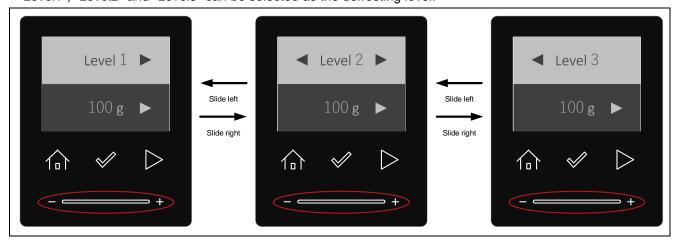


Figure 5-15 Setting the level of defrosting

5.4.3.2 Move the cursor

While the Defrost detail setting screen is displayed, touching the "select" button can move the cursor. The item with a light-colored background is selected.

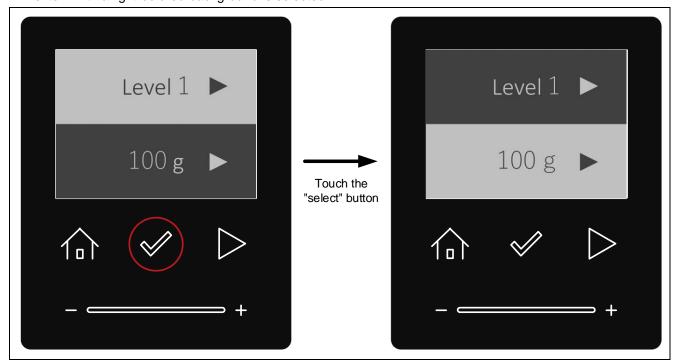


Figure 5-16 How to operate the cursor on the Defrost detail setting screen

5.4.3.3 Set the number of grams

While the cursor is on the lower side, the number of grams can be set with the slider. "100g", "200g" and "300g" can be selected as the defrosting amount.

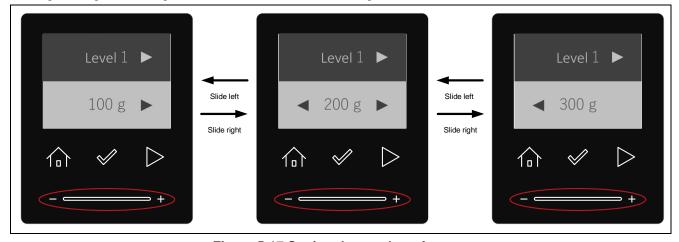


Figure 5-17 Setting the number of grams

5.4.3.4 Start defrosting

While the Defrost detail setting screen is displayed and the cursor is on the lower side, touching the "start" button can start defrosting.

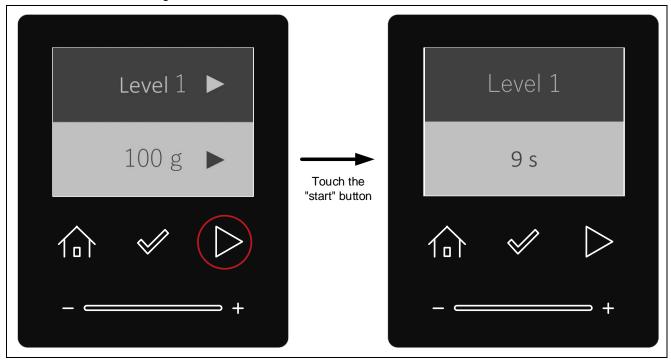


Figure 5-18 Start defrosting in Manual mode

5.4.4 Select Fish

While "Fish" is selected on the Defrost mode selection screen, touching the "start" button can start defrosting with the settings for "Fish".

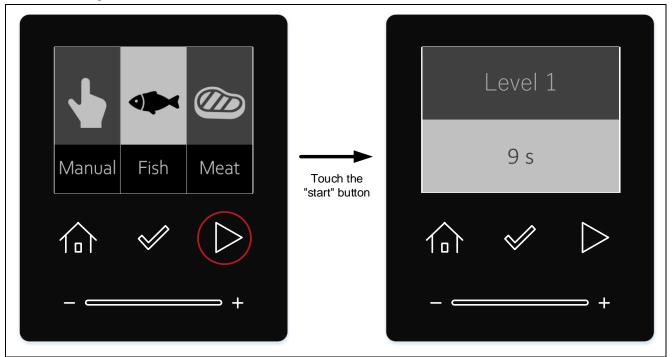


Figure 5-19 Start defrosting in Fish mode

5.4.5 Select Meat

While "Meat" is selected on the Defrost mode selection screen, touching the "start" button can start defrosting with the settings for "Meat".

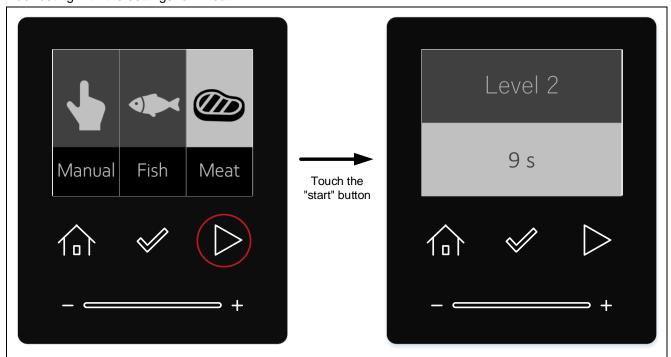


Figure 5-20 Start defrosting in Meat mode

5.5 Recipe setting

5.5.1 Move to recipe selection screen

While "Recipe" is selected on the menu screen, touching the "select" button can move to the Recipe selection screen.

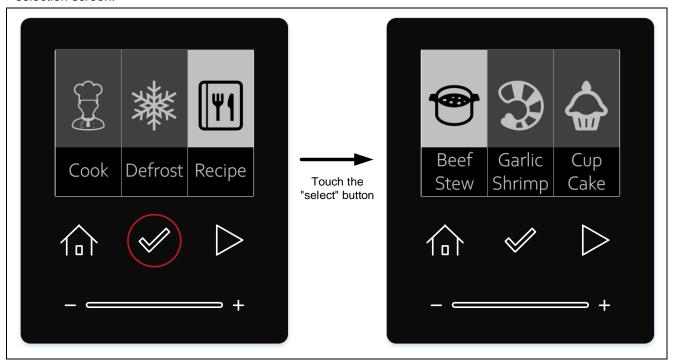


Figure 5-21 Move to the Recipe selection screen

5.5.2 Select recipe

While the Recipe selection screen is displayed, "Beef Stew", "Garlic Shrimp" or "Cup Cake" can be selected with the slider operation.

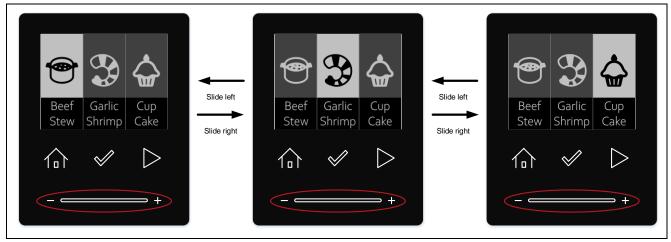


Figure 5-22 How to operate the Recipe selection screen

5.5.3 Select Beef Stew

While "Beef Stew" is selected on the Recipe selection screen, touching the "start" button can start cooking for the Settings for Beef Stew.

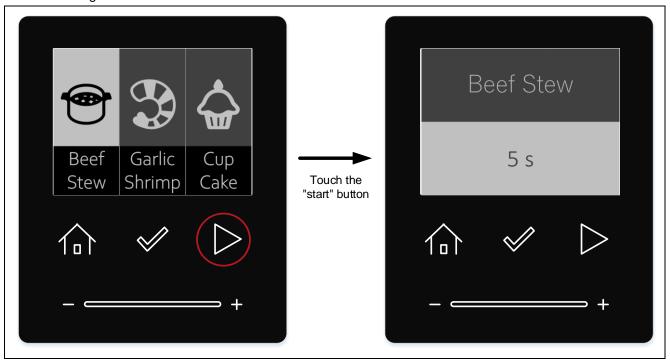


Figure 5-23 Start cooking in Beef Stew mode

5.5.4 Select Garlic Shrimp

While "Garlic Shrimp" is selected on the Recipe selection screen, touching the "start" button can start cooking for the Settings for Garlic Shrimp.

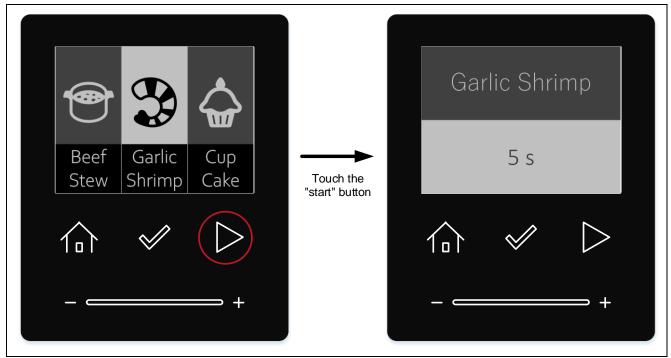


Figure 5-24 Start cooking in Garlic Shrimp mode

5.5.5 Select Cup Cake

While "Cup Cake" is selected on the Recipe selection screen, touching the "start" button can start cooking for the Settings for Cup Cake.

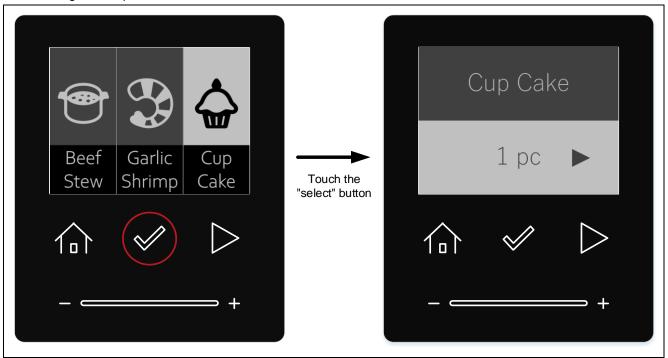


Figure 5-25 Move to the Cup Cake detail setting screen

5.5.5.1 Set the number of cupcakes

You can set the number of cupcakes with the slider.

"1pc", "2pcs" and "3pcs" can be selected as the cooking amount.

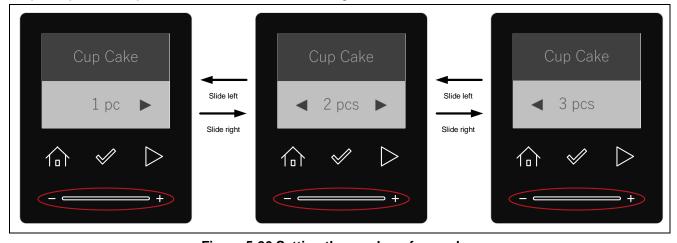


Figure 5-26 Setting the number of cupcakes

5.5.5.2 Start cooking

While the Cup Cake detail setting screen is displayed, touching the "start" button can start cooking.

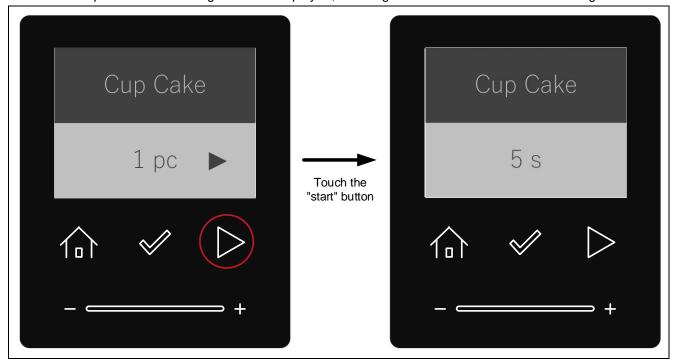


Figure 5-27 Start cooking in Cup Cake mode

5.6 About the "home" button

The "home" button returns to the menu screen from any screen.

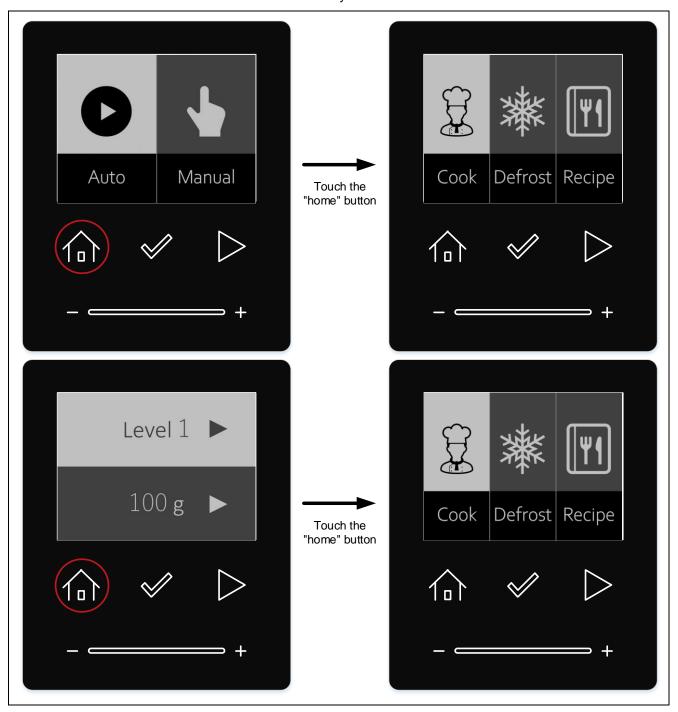


Figure 5-28 Example of "home" button operation

5.7 About the cooking completion screen

While completed cooking, the cooking completion screen is displayed for 3 seconds. After that, move to the menu screen automatically.

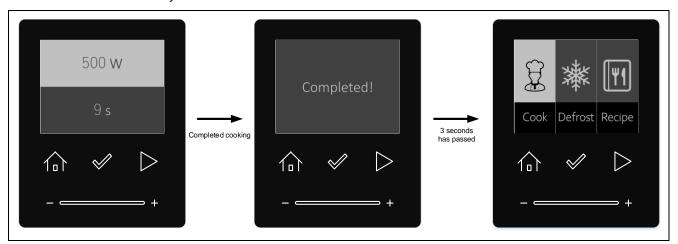


Figure 5-29 Example of cooking completion operation

5.8 Smart wakeup function

If no touch operation is performed for 10 seconds, the LCD is turned off and the RX140 transitions to software standby mode. For detail on Smart Wakeup, refer to "RX140 Group Smart Wakeup Solution".

Long touch any button to return to the previous screen.

6. Reference Documents

- RX140 Group User's Manual: Hardware (R01UH0905)
- RX140 Group Smart Wakeup Solution (R11AN0613)
- RX Family Using QE and FIT to Develop Capacitive Touch Applications (R01AN4516)
- RX Family QE for Display GUI Display Application Development Guide (R20AN0688)

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Revision History

		Description	Description	
Rev.	Date	Page	Summary	
1.00	Apr.24.23	_	First edition	

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

- 6. Voltage application waveform at input pin
 - Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
- 7. Prohibition of access to reserved addresses
 - Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not quaranteed.
- 8. Differences between products
 - Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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